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About GOULD Electronics

Electrodeposited copper foil has been used for half a century as raw material in microelectronics. GOULD was quick to recognize the opportunities and prospects that would present themselves in the PCB industry and to strategically invest in the technology of electroplating. As a result GOULD is one of the world's leading supplier of high quality copper foil products. A large number of top-notch copper clad and PCB manufacturers are customers of GOULD. Thanks to our technological competence, quality, a high degree of customer orientation and our international orientation we have achieved a place among the top ED copper foil suppliers in the world.

1961

Foundation of Electrometall GmbH

1963

First production of ED copper foil in Eichstetten, Germany

1981

Nippon Mining becomes a JV-Partner

1993

Launch of CAC® business

2004

Transfer of assets from Gould US to NMM Tokyo

2006

Gould establishes HPCF to support US market

2008

Gould restructures its business

2011

50 years celebration

2012

DIN EN ISO 50001 certification

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